IN THE CLAIMS:

Cancel claims 1-5 and 10-15 without prejudice or disclaimer.

Amend the claims as follows:

6. (amended) The method of claim 8 where the dielectric layer is between about 5 and
50 microns thick.

7. (amended) The method of claim 8 wherein photopolymeric material is an epoxy based resin.

8. (amended) A method of forming a capacitor on a printed circuit board, the method comprising the steps of: [The method of claim 5 wherein the step of patterning the photopolymeric film comprises:]

providing a first metal plate on a dielectric substrate, said first metal plate having a first region and a second region about the first region,

applying a photopolymeric film of a photosensitive polymer over said first metal plate, said photopolymeric film having a substantially uniform thickness,

patterning the photopolymeric film to define a dielectric layer overlying the first region of the first metal plate and to expose the second region of the first metal plate by selectively irradiating a first portion of said photopolymeric film overlying the first region of the first metal plate while

avoiding irradiation of a remaining portion, said first portion being irradiated by actinic radiation effective to initiate polymerization of the photosensitive polymer, said portion being sized and shaped corresponding to the dielectric layer,

heating the photopolymeric layer to partially cure the first portion,

removing the remaining portion to expose the first metal plate about the partially cured, first portion, and

further heating the partially cured first portion to further cure the photosensitive polymeric material,

plating a second metal plate onto the dielectric layer and the second region of the first metal plate such that the dielectric layer is enclosed within the first metal plate and the second metal plate,

patterning said second metal plate to form an upper electrode overlying the dielectric layer and electrically isolated from the first metal plate and to concurrently pattern the second metal plate to form a lower electrode underlying the dielectric layer and cooperating with the upper electrode and the dielectric layer to form a capacitor,

applying a polymeric coating overlying the capacitor,

defining a via in said polymeric coating communicating with said upper electrode, and

depositing metal into the via to form an electrical connection to the upper electrode.

9. (amended) A method of claim 8 wherein the first metal plate and the second metal plate are formed of copper.